**并转串芯片调研**

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| **型号** | **品牌** | **速度** | **转换数** | **协议** | **价格** | **备注** |
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**串转并芯片调研**

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| **型号** | **品牌** | **速度** | **转换数** | **协议** | **价格** | **备注** |
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